

保密等级：机密

SPECIFICATION

产品规格书

SKI.WB800DS2.1

IEEE 802.11b/g/n/ac/ax 1T1R USB+SDIO Wi-Fi

Integrated BT 5.0

2.4G/5G Dual Band Module

Approved by Shikun		
Checked by 审核	Rechecked by 复审	Approved by 批准

Please send the original back to us after you have approved and signed.

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Comments 确认意见	Approved by 批准签字	Company's seal 盖章
Customer's Name:		

REVISION HISTORY.

VERSION	DATE	BOARD ID	PAGE	DESCRIPTION	AUTHOR
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1. Introduction (简介)

SKI.WB800DS2.1 module is based on AIC8800M solution. SKI.WB800DS2.1 is a Wi-Fi 6 / BT 5.0 combo low-power, high-performance and high-integrated dual band wireless communication module which is designed for meeting the customers' needs of small size and low cost. This module supports both WLAN and BT functions. Its WLAN/BT function supports the USB 2.0 / SDIO 2.0 interface, and its BT function supports the UART interface, and the module meets the requirements of standard protocol IEEE 802.11 b/g/n/ac/ax. Such units as power management, power amplifier and low-noise amplifier are integrated in the main chip of the module. Its WLAN PHY rate is up to 266.8Mbps@TX. The module can be applied in smart sound boxes, set-top boxes, game machines, printers, IP cameras, tachographs, and other smart equipment. This documentation describes the engineering requirements specification.

SKI.WB800DS2.1 模块基于 AIC8800D 方案。SKI.WB800DS2.1 是一款 Wi-Fi 6 / BT 5.0 组合的低功耗、高性能、高集成度双频无线通信模块，专为满足客户小尺寸、低成本的需求而设计。该模块支持 WLAN 和 BT 功能。WLAN/BT 功能支持 USB 2.0 / SDIO 2.0 接口，BT 功能支持 UART 接口，满足 IEEE 802.11 b/g/n/ac/ax 标准协议要求。本文档描述了工程要求规范。

2. Features (特性)

	IEEE Std. 802.11b/g
	IEEE Std. 802.11n
	IEEE Std. 802.11ac
	IEEE Std. 802.11ax
	BT 5.0
Chip Solution 芯片方案	AIC8800D
Band 波段	2.4GHz/ 5GHz
Dimensions 尺寸	12mm×12mm×1.8mm

Model 型号	Installation Mode 安装方式	Protocol I 支持标准	Frequency 频段	Antenna 天线	Remark 备注
SKI.WB800DS2.1	SMD	IEEE 802.11b/g/n/ac/ax BT 5.0	2.4GHz/5GHz	LGA Pad*1	12mm×12mm× 1.8mm

3. Block Diagram (结构框图)

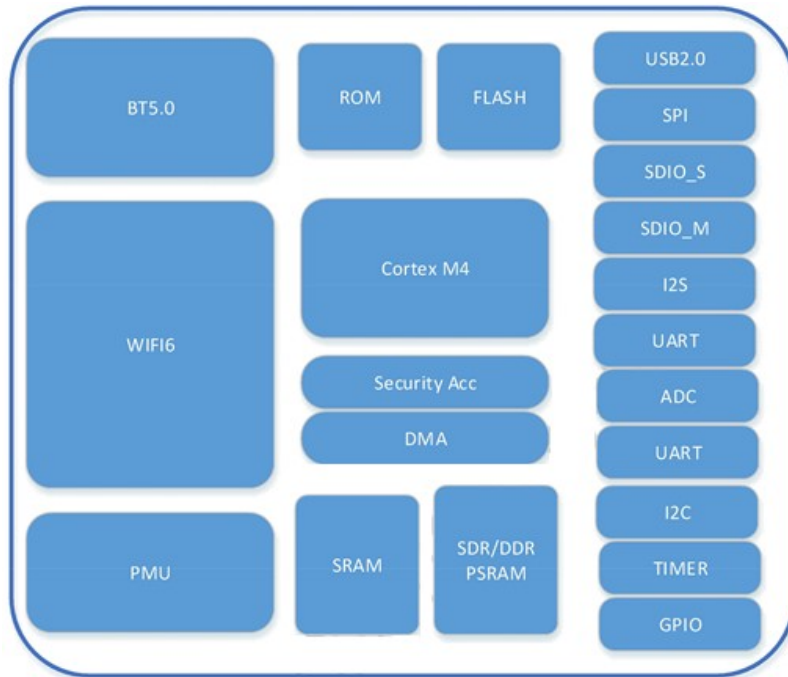
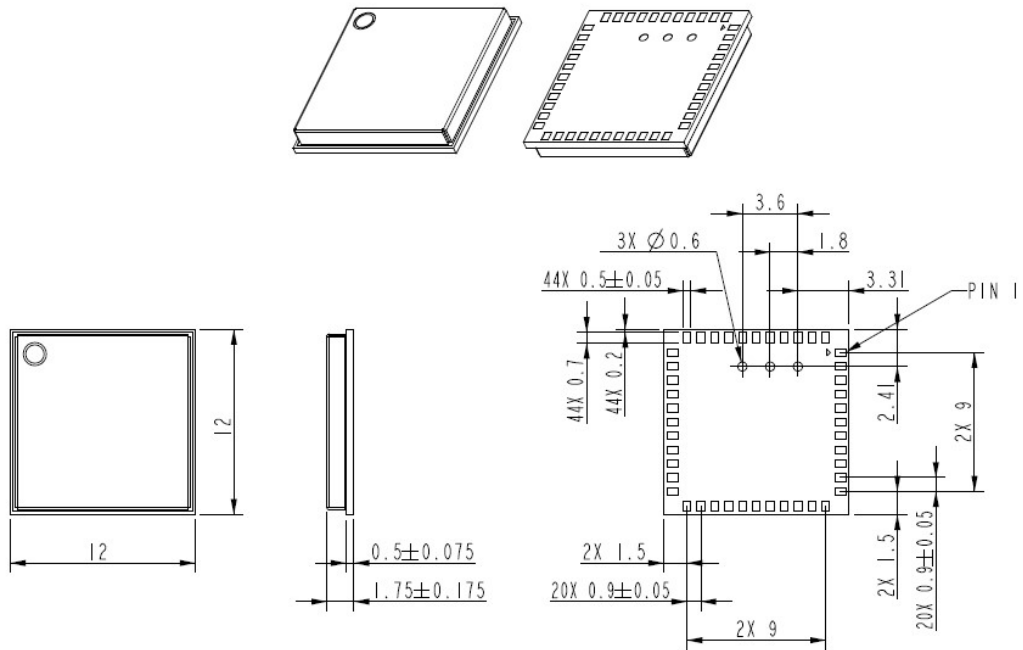


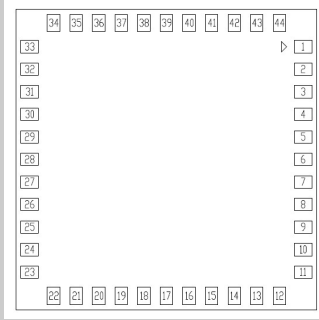
Figure 1 SKI.WB800DS2.1 Block Diagram

4. Package Outline and Mounting (外形及安装尺寸)



TOLERANCE UNLESS OTHERWISE SPECIFIED: ±0.1mm

5. Pin Definition (引脚定义)



模组的 LGA44 PAD 底视图

PIN	SYMBOL	Type	DESCRIPTION
1	GND	G	Grounded
2	WLAN_BT_ANT	RF	WLAN/BT RF I/O Port
3	GND	G	Grounded
4	NC	-	-
5	NC	-	-
6	GPIOB5	I/O	GPIOB5 PIN
7	GPIOB3	I/O	GPIOB3 PIN
8	GPIOB1	I/O	GPIOB1 PIN
9	VBAT	P	Voltage Input of Main Power Supply
10	USB_DM	I/O	Wi-Fi USB DM Pin
11	USB_DP	I/O	Wi-Fi USB DP Pin
12	PWR_KEY	I	Power Enabling/Disabling
13	D_WAKE_H	I/O	Wi-Fi Wake Up Host
14	SDIO_D2	I/O	Wi-Fi SDIO Port
15	SDIO_D3	I/O	Wi-Fi SDIO Port
16	SDIO_CMD	I/O	Wi-Fi SDIO Port
17	SDIO_CLK	I/O	Wi-Fi SDIO Port
18	SDIO_D0	I/O	Wi-Fi SDIO Port
19	SDIO_D1	I/O	Wi-Fi SDIO Port
20	GND	G	Ground
21	NC	-	-
22	VIO	P	VDDIO
23	NC	-	-
24	GPIOB4	I/O	GPIOB4 PIN
25	NC	-	-
26	NC	-	-
27	NC	-	-

28	NC	-	-
29	UART0_TX	O	UART0 TX (Test/Download Use)
30	UART0_RX	I	UART0 RX (Test/Download Use)
31	GND	G	Ground
32	NC	-	-
33	GND	G	Ground
34	GPIOB7	I/O	GPIOB7 PIN
35	GPIOB6	I/O	GPIOB6 PIN
36	GND	G	Ground
37	NC	-	-
38	NC	-	-
39	NC	-	-
40	NC	-	-
41	UART1 RTS	I/O	BT UART1 RTS
42	UART1 TX	I/O	BT UART1 TX
43	UART1 RX	I/O	BT UART1 RX
44	UART1 CTS	I/O	BT UART1 CTS

6. Product Pictures (实物图片)

正视图 (top view)

背视图 (bottom view)

7. Key Materials (关键物料)

序号	关键件名称	型号	规格/材料	备注
1	集成电路	AIC8800D	48-QFN	
2	PCB	SKI.WB800DS2.1	FR-4,4LAY	
3	晶体振荡器	CN4026M00012T2115181	26MHz	

8. General Requirements (一般要求)

No.	Feature	Description
8-1	Operation Voltage 工作电压范围	3.3V+/-0.3
8-2	Current Consumption 最大电流	TBD
8-3	Ripple 纹波	TBD
8-4	Operation Temperature 工作温度范围	-20°C to +80°C
8-5	Antenna Type 天线类型	External antenna
8-6	SDIO 2.0/USB2.0/UART Interface	SDIO 2.0/USB2.0/UART 接口
8-7	Storage Temperature 存储温度	-40°C to +85°C

9. Electrical Characteristics (电气特性)

除非另有说明，电气规范试验都在下列条件下进行：

环境条件温度：25°C ± 5°C；

电源电压：模块输入电压 3.3V+/-0.3；

The Test for electrical specification was performed under the following condition unless otherwise specified:

Ambient condition Temperature :25°C ± 5°C；

Power supply voltages: 3.3V+/-0.3 input power at the Module;

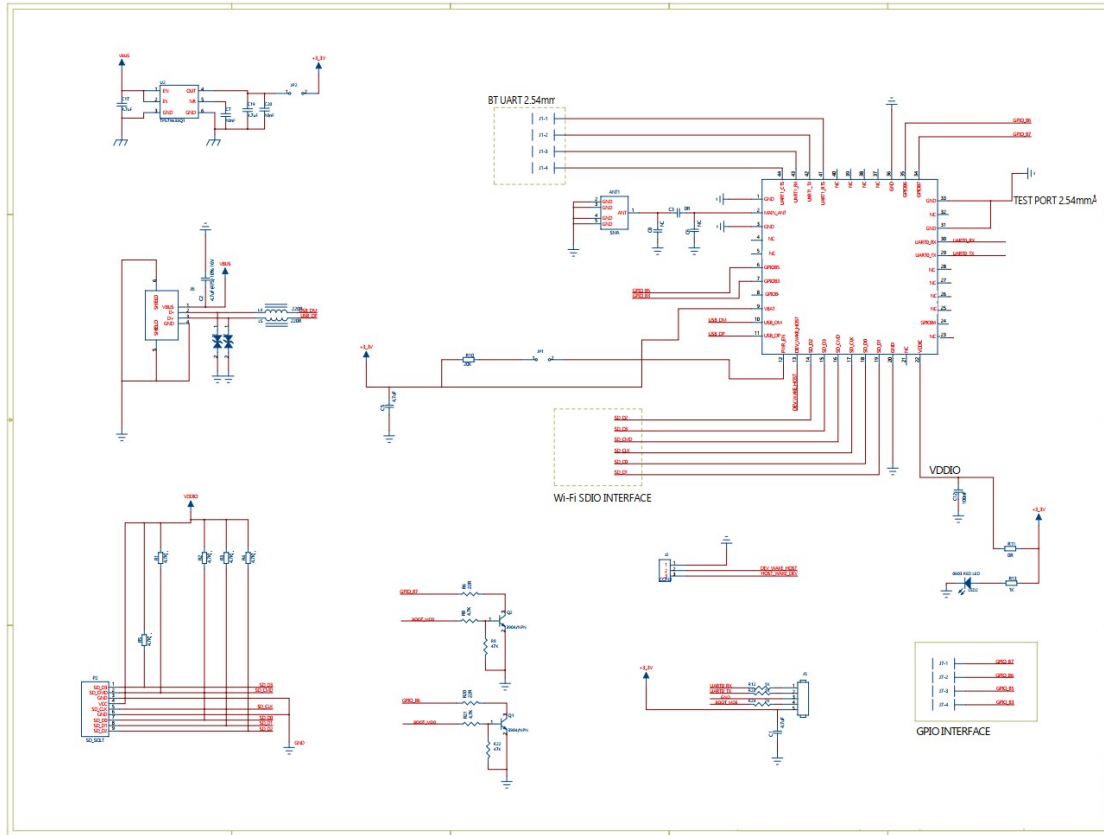
9.1 WLAN Parameters

Mode	Protocol Standard	Description
Modulation	802.11 ac/ax	OFDM/OFDMA With 256-QAM, 64-QAM, 16-QAM,
	802.11 ax	OFDM/OFDMA 1024-QAM
	802.11 b	DSSS With DQPSK, DBPSK, CCK
	802.11 g/n	OFDM/OFDMA With 64-QAM, 16-QAM, QPSK, BPSK
Data rate	802.11 a/ac	HT/VHT 20,40 : MCS0-MCS9
	802.11 ax	HE20/40 : MCS0-MCS11
	802.11 b	1,2,5.5,11Mbps
	802.11 g	6,9,12,18,24,36,48,54Mbps
	802.11 n	HT20 : MCS0-MCS7, 72.2Mbps
Output Power	802.11 ax	TDB (5GHz@ HE40 MCS9)
	802.11 ax	TDB (5GHz@ HE20 MCS9)
	802.11 b	18dBm ± 1.5dBm (2.4GHz@11Mbps)
	802.11 g	15dBm ± 1.5dBm (2.4GHz@54Mbps)
	802.11 n	16dBm ± 1.5dBm (2.4GHz@HT40, MCS7)
	802.11 ax	15dBm ± 1.5dBm (2.4GHz@HE40, MCS9)
Receiver	802.11 ax	TDB (5GHz@ HE40 MCS9)
	802.11 ac	TDB (5GHz@ VHT40 MCS9)
Sensitivity	802.11 b	-85dBm ± 1dBm (2.4GHz@11Mbps, CCK, 8%PER)
	802.11 g	-73dBm ± 1dBm (2.4GHz@54Mbps, OFDM, 10%PER)
	802.11 n	-72dBm ± 1dBm (2.4GHz@HT40, MCS7, 10%PER)
	802.11 ax	-67dBm ± 1dBm (2.4GHz@HE40, MCS9, 10%PER)

9.6 Bluetooth Section

Mode	Description
Modulation	GFSK(1Mbps), $\pi/4$ -DPSK(2Mbps), 8DQPSK(3Mbps)
Output Power	$0 \leq \text{Output Power} \leq +13\text{dBm}$
Receiver Sensitivity	GFSK, 0.1% BER 1Mbps -95dBm

10. Reference Design (参考设计)



10.1 External Antenna

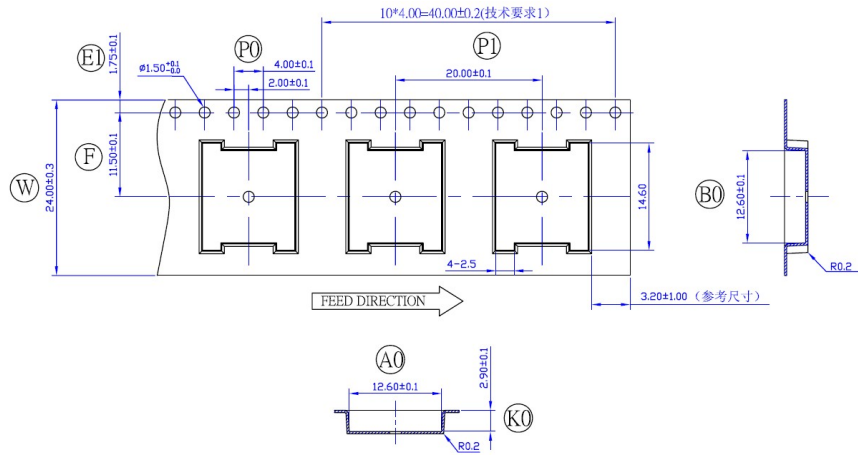
When the customer selects an external antenna, the external antenna selected must meet the parameter requirements specified in Table 10-1-1.

Table 10-1-1 Requirements on External Antenna Parameters

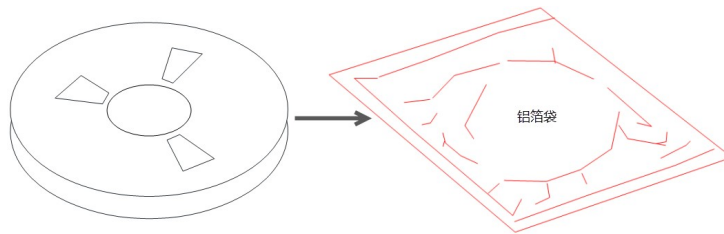
Item	Parameter
Antenna operating frequency	2.4GHz/ 5GHz
Impedance	50Ω
Return Loss	≤-10dB

11. Package (包装)

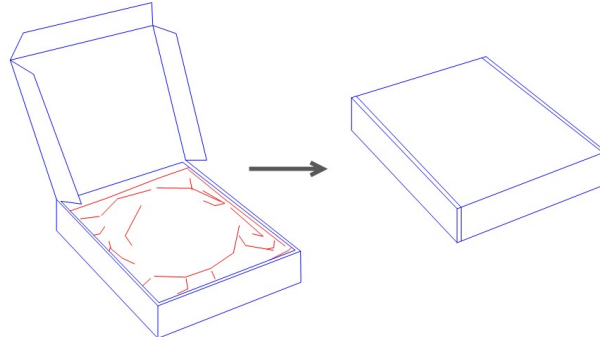
(1) 编带包装



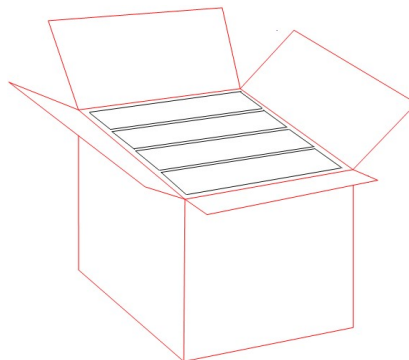
(2) 胶带包装



(3) 内盒包装



(4) 外箱包装 354*250*362mm



(5) 最小包装量 1000PCS/盘*4 盘/箱=4000PCS/箱